AGUIMEA Passion for Technology

European Space Components Conference ESCCON 2019

ESTEC, March 11 - 13, 2019

COMPANY OVERVIEW

ΛΓΟΙΙΜΕΛ Passion for Technology

Design House specialized in parts and systems for space and **hi-rel** applications

Sister companies in Madrid (ES) and Frankfurt Oder (DE)

Suppliers of electronics, microelectronics and mechanisms

Strong **R&D** activity and **product-oriented** strategy



EUR 10.5M revenues in FY19 42 employees





RAD-HARD ASICs/FPGAs

WE ARE FABLESS

Experts in analog, digital and mixed signal

Own proprietary rad-hard IPs in several technologies. Unrestricted access to rad-hard standard libraries

Flexible supply chain. Packaging and quality flows adapted to customer needs

One-stop shop. Turnkey solutions



Cost reduction and better performance in your equipment by:

Replacing costly flight FPGAs by digital ASICs in high-volume applications \rightarrow FPGA to ASIC conversion Integrating many functionalities into a single chip

Reducing the amount of EEE parts in electronic equipment



www.arguimea.com

RAD-HARD ASICs/FPGAs Main projects

REDSAT ASIC chipset ELSA	Management of the Multichip Control Module (MCCM) of a reconfigurable active array antenna (Ku Band). 600+ chips in a single mission (Hispasat 36W-1 GEO comsat)	C AIRBUS DEFENCE & SPACE
COSMIC VISION	Front End Readout ASIC for Cosmic Vision Instrumentation Payload	Cesa
RTU ASIC	Control and management of Data I/O Interface, Battery Charge Control and Power Distribution in satellite constellations.	6p
QUANTUM Beam Hopping Enabled Digital ASIC	Control and management of RF subassemblies while enabling fast beam hopping in active array antenna	C AIRBUS DEFENCE & SPACE
QUANTUM FPGAs	Design, programming and verification of two space FPGAs according to ECSS-Q-60B standard	C AIRBUS DEFENCE & SPACE
TMTC ASIC	Mixed-signal ASIC for telemetry and telecommand handling for general purpose in satellites	AIRBUS DEFENCE & SPACE
RTG4 FPGAs	Verification tools to corroborate good implementation of SEU/SET-Mitigation Techniques in 3rd/4th Generation Flash FPGAs. Validation of the effectiveness of these tools through Heavy Ion and proton radiation.	esa

RAD-HARD IC PRODUCTS LVDS for SpaceWire networks

Data transmission along twisted pair cables at **very high data-rates** and **excellent EMI performance**

- ARQUIMEA LVDS family of ICs: Driver, Receiver, Transceiver, Repeater
- 0.25-um BiCMOS technology process. Fully European supply chain
- Full compliance with the ANSI_EIA/TIA644A standard
- Over 500Mbps data transfer rate per channel
- 3.3V single power supply
- Small propagation delay, low channel-to-channel skew and low jitter
- Extended input common mode range from -4V to +5V
- Cold-spare in all pins
- Fail Safe protection
- Input hysteresis implemented at the receiver side
- TID: 300 kRad(Si)
- SEL immune up to LET of 60 MeV*cm²/mg
- BER down to 1E⁻¹³ err/bit in GEO orbit
- ESD protection above 8kV HBM

ECSS Qualification ongoing. FMs available in Q3-19



LVDS Octal Repeater





RAD-HARD IC PRODUCTS 10/100 Mbps Ethernet PHY Transceiver

First rad-hard Ethernet PHY in the market

Standard solution for launchers, satellites and spacecraft

Compatible with **Time Sensitive Networks (TSN)** and **Time-Triggered Ethernet** for **deterministic realtime communications**

- Compatible with IEEE 802.3 10BASE-T, IEEE 802.3 100BASE-TX and ANSI X3.263-1995
- Integrated high performance 100 Mb/s clock recovery circuitry requiring no external filters
- Programmable loopback modes for easy system diagnostics
- 3.3V/1.8V power supply
- Cold spare
- MII/RMII MAC communication interface
- MI interface for MAC management and diagnostics
- TID > 100 kRad
- SEU threshold LET > 30MeV/mg/cm²
- SEU Error Rate < 10⁻¹² errors/bit-day (at < 70 MeV/mg/cm²)
- SEL immune up to LET of 60MeV/mg/cm²
- QFP64 package



Prototypes available. Seeking funding for ESCC qualification

RAD-HARD IC PRODUCTS 2.5 Gbps SERDES Transceiver

Used in **high-speed communications** to compensate for limited input/output.

Data transmission over a single line or a differential pair to **minimize the number of** I/O pins and interconnects.

- 1.6 to 2.5-Gbps transmission/reception speed
- Interfaces to backplane, copper cables or optical converters
- On-Chip 8-Bit/10-Bit Encoding/Decoding, Comma Detect
- Low Power: < 500mW (Power consumption < 5mW if the device is disabled)
- TID > 100 kRad
- SEU threshold LET > 30MeV/mg/cm²
- SEU Error Rate < 10⁻¹⁰ errors/bit-day (at <70 MeV/mg/cm²)
- SEL immune up to LET of 70MeV/mg/cm²
- BER < 10^{-12} for GEO orbit
- Available in space-grade ceramic (CQFP68) and plastic packages

(*) Parameters to be confirmed

Under development. EMs available in Q3-19



RAD-HARD MICROELECTRONICS AND NEW SPACE

There are may alternatives open for EEE Parts in New Space:

Radiation hardening \rightarrow Up-screened COTS vs Rad Tolerant vs Rad Hard

Packaging \rightarrow Ceramic vs hi-rel plastic

Qualification levels \rightarrow ESCC vs reduced evaluation

We propose Chinese flight-proven parts with independent reduced ESCC evaluation at very competitive prices:







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Adrien Frouin

Senior Product Manager

afrouin@arquimea.com

+34 637 003 887

www.arquimea.com